

Yi Luo

List of Publications by Year in descending order

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Version: 2024-02-01

24
papers

223
citations

1684188

5
h-index

1058476

14
g-index

24
all docs

24
docs citations

24
times ranked

183
citing authors

#	ARTICLE	IF	CITATIONS
1	Capillary and thermal performance enhancement of rectangular grooved micro heat pipe with micro pillars. International Journal of Heat and Mass Transfer, 2020, 153, 119581.	4.8	18
2	Packaging flat micro heat pipe using low melting point alloy. , 2018, , .		0
3	Thermal performance optimization of Si micro flat heat pipes by Boxâ€Behnken design. Microsystem Technologies, 2018, 24, 3085-3094.	2.0	3
4	Experimental investigation on the thermal performance of Si micro-heat pipe with different cross-sections. Modern Physics Letters B, 2017, 31, 1750279.	1.9	2
5	New encapsulation method using low-melting-point alloy for sealing micro heat pipes. Journal of Mechanical Science and Technology, 2017, 31, 2621-2626.	1.5	2
6	Thermal behavior of silicon-copper micro vapor chamber for high power LEDs. Optoelectronics Letters, 2016, 12, 124-127.	0.8	3
7	A Novel Flat Micro Heat Pipe With a Patterned Glass Cover. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1051-1055.	2.5	3
8	Experimental study on high-power LEDs integrated with micro heat pipe. Optoelectronics Letters, 2016, 12, 31-34.	0.8	1
9	Charging method of micro heat pipe for highâ€power lightâ€emitting diode. Micro and Nano Letters, 2015, 10, 518-522.	1.3	6
10	Experimental Investigation of Thermal Conduction Performance on Silicon-Based Micro Flat Heat Pipe. Key Engineering Materials, 2015, 645-646, 1032-1037.	0.4	2
11	Local thermal-assisted ultrasonic embossing for the fabrication of polymer microstructures. Microsystem Technologies, 2015, 21, 1101-1110.	2.0	5
12	Thermal behavior investigation of silicon-Pyrex micro heat pipe. AIP Advances, 2014, 4, 031305.	1.3	6
13	Using silicon molds for ultrasonic embossing on Polymethyl Methacrylate (PMMA) substrates. Microsystem Technologies, 2013, 19, 609-616.	2.0	11
14	Fixture design and sequence analysis for low stress assembly of precision miniature devices without disturbance. , 2013, , .		0
15	Study of Double-Side Ultrasonic Embossing for Fabrication of Microstructures on Thermoplastic Polymer Substrates. PLoS ONE, 2013, 8, e61647.	2.5	13
16	A low temperature ultrasonic bonding method for PMMA microfluidic chips. Microsystem Technologies, 2010, 16, 533-541.	2.0	25
17	Machine Vision Technology for Measurement of Miniature Parts in Narrow Space Using Borescope. , 2010, , .		9
18	Temperature and force precise control system for automatic indium-sealing device. , 2010, , .		0

#	ARTICLE	IF	CITATIONS
19	Research for hole-peg assembly based on machine vision and flexible mechanism. , 2010, , .		3
20	A method of pre-tightening force control for the mini-bolt joint precision assembly. , 2010, , .		0
21	Study on Heating Process of Ultrasonic Welding for Thermoplastics. Journal of Thermoplastic Composite Materials, 2010, 23, 647-664.	4.2	103
22	Ultrasonic bonding of polymer microfluidic chips. , 2008, , .		5
23	The Process of Automatically Fabricating Polymer Microfluidic Chips. , 2006, , .		0
24	Fabrication and Thermal Performance of Copper Pillars Modified Micro Heat Pipe (MHP). Key Engineering Materials, 0, 645-646, 208-215.	0.4	3